



DESCRIPTION

The AP8022C is a current consisting of a Pulse Width Modulator (PWM) controller and a power MOSFET, specifically designed for a high-performance off-line converter with minimal external components.

The AP8022C offers complete protection coverage with an automatic self-recovery feature, including Cycle-by-Cycle current limiting (OCP), over-temperature protection (OTP), under-voltage lockout protection (UVLO), VDD over-voltage protection (OVP), and soft-start. Burst mode operation and the device's very low consumption help to meet the standby energy-saving regulations. Excellent EMI performance is achieved with frequency modulation. The device consists of a high-voltage start-up circuit to reduce the system set-up time.

The AP8022C provides an advanced platform well-suited for low-standby power and cost-effective flyback converters.

The AP8022C is available in DIP8 and SOP8 packages.

ORDERING INFORMATION

Package Type	Part Number	
DIP8 SPQ:50pcs/Tube	P8	AP8022CP8VU
SOP8 SPQ: 4000pcs/R	M8	AP8022CM8VR
Note	V: Halogen-free Package U: Tube R: Tape & Reel	
AiT provides all RoHS products		

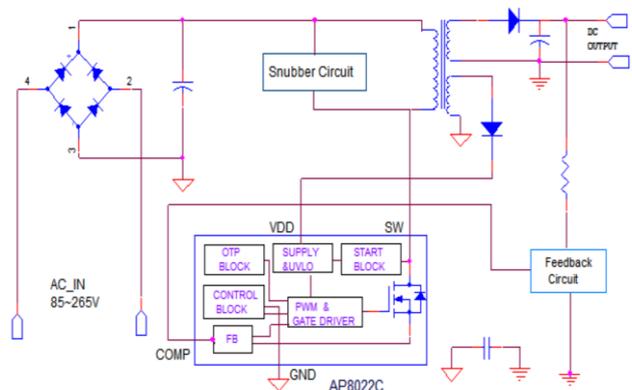
FEATURES

- Integrated 700V avalanche-rugged power MOSFET
- 85V to 265V wide range AC voltage input
- 60 KHz fixed switching frequency
- Current mode PWM control method
- Integrated high-voltage startup and switching circuit
- 9V~39V wide VDD operating voltage range
- Excellent Protection:
 - Over Current Protection (OCP)
 - Over Temperature Protection (OTP)
 - V_{DD} over-voltage protection (OVP)
 - Under-voltage lockout protection (UVLO)

APPLICATION

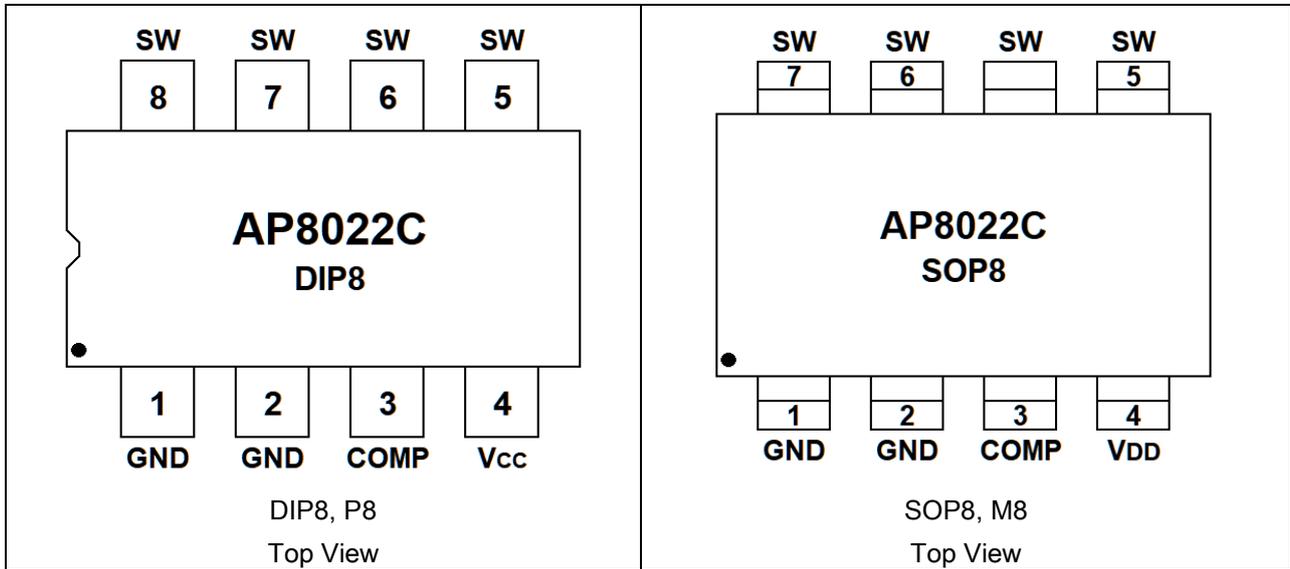
- Electromagnetic Oven power supplies
- Small household application power supplies
- DVB/DVD Power

TYPICAL APPLICATION





PIN DESCRIPTION



Pin #		Symbol	Function
SOP8	DIP8		
1, 2	1, 2	GND	Ground
3	3	COMP	Voltage feedback. By connecting an opto-coupler to close the control loop and achieve the regulation.
4	4	V _{DD}	Positive Supply voltage Input.
5	-	NC	No connection
6,7,8	5,6,7,8	SW	The SW pin is designed to connect directly to the primary lead of the transformer.



TYPICAL POWER

Package	85~265 V _{AC}	180~265 V _{AC}
SOP8	5W	8W
DIP8	12W	20W

For output power above 10W, it is recommended to add heat dissipation measures according to the actual solution

ABSOLUTE MAXIMUM RATINGS

High-Voltage Pin, SW	-0.3V~650V	
Supply voltage Pin V _{DD}	-0.3V~40V	
Continuous drain current, I _D	Internally limited	
Embedded current, I _{VDD}	10mA	
Feedback current, I _{COMP}	3mA	
Junction Temperature	-40°C~150°C	
Storage Temperature	-55°C~150°C	
Lead Temperature (Soldering, 10secs)	260°C	
Package Thermal Resistance, R _{thJC}	DIP8	15°C/W
	SOP8	25°C/W
Power Dissipation, P _D	DIP8	1W
	SOP8	0.5W
Electrostatic Discharge Human Body Mode (HBM, ESDA/JEDEC JDS-001-2014)	±2kV	

Stress beyond above above-listed "Absolute Maximum Ratings" may lead to permanent damage to the device. These are stress ratings only, and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



ELECTRICAL CHARACTERISTICS

$T_J = 25^\circ\text{C}$, $V_{DD} = 15\text{ V}$, unless otherwise specified

Power section

Parameter	Symbol	Conditions	Min.	Typ.	Max	Unit
VDMOS Breakdown Voltage	B_{VDSS}	$I_{SW} = 250\mu\text{A}$	650	-		V
Static Drain-Source off Current	I_{OFF}	$V_{SW} = 550\text{V}$			100	μA
Static Drain-Source on Resistance	R_{DSON}	$I_{SW} = 400\text{mA}$, $T_J = 25^\circ\text{C}$	5	-	16	Ω

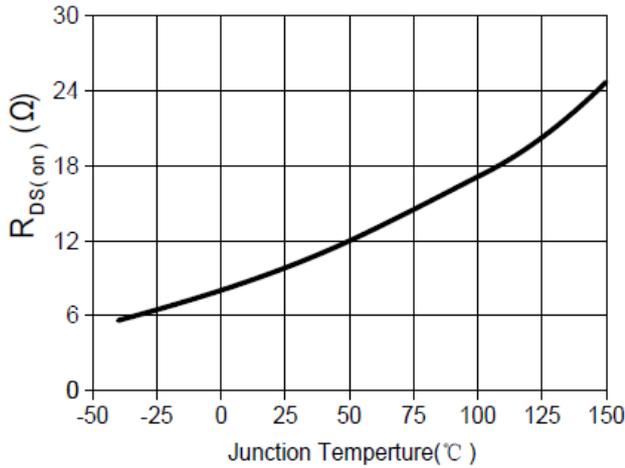
Control section

Parameter	Symbol	Conditions	Min.	Typ.	Max	Unit
UVLO SECTION						
V_{DD} Start Threshold Voltage	V_{START}	$V_{COMP} = 0\text{V}$	13	14.5	16	V
V_{DD} Stop Threshold Voltage	V_{STOP}	$V_{COMP} = 0\text{V}$	7	8	9	V
V_{DD} Threshold Hysteresis	V_{HYS}			4.5		V
V_{DD} Reset Voltage	V_{RST}		5.5	6	6.5	V
OSCILLATOR SECTION						
Initial Accuracy	F_{OSC}	$T_A = 25^\circ\text{C}$	54	60	66	kHz
FEEDBACK SECTION						
Feedback Shutdown Current	I_{COMP}			1.2		mA
COMP Pin Input Impedance	R_{COMP}	$I_D = 0\text{mA}$		1.23		k Ω
CURRENT LIMIT SECTION						
Peak Current Limit	I_{LIM}	$T_A = 25^\circ\text{C}$	0.56	0.70	0.84	A
V_{DD} Over Voltage Threshold	V_{DDOVP}		37.5	39	40	V
Leading Edge Blanking	t_{LEB}	LEB time		300		ns
Minimum Turn On Time	$T_{on(min)}$	$V_{DD} = 18\text{V}$		700		ns
Soft-start Time	t_{SS}			7.5		ms
PROTECTION SECTION						
Thermal Shutdown Temperature	T_{SD}		145	-		$^\circ\text{C}$
Thermal Shutdown Hysteresis	T_{HYST}			30		$^\circ\text{C}$
SUPPLY CURRENT SECTION						
Startup Charging Current (SW pin)	I_{CH}	$V_{DRAIN} = 105\text{V}$, $V_{COMP} = \text{GND}$, $V_{DD} = 12\text{V}$		-500		μA
Operating Supply Current, Switching	I_{DD}	$V_{DD} = 16\text{V}$, $V_{COMP} = 0\text{V}$		4		mA
Operating Voltage Range	V_{DD}	After turn-on	10		35	V
Power Suspends	P_{SPD}			120		mW

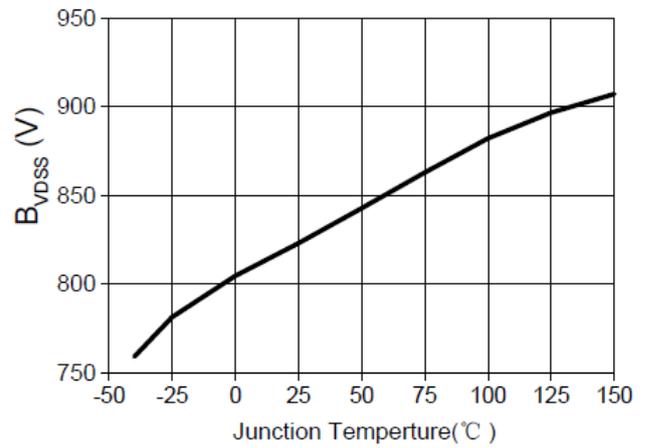


TYPICAL PERFORMANCE CHARACTERISTICS

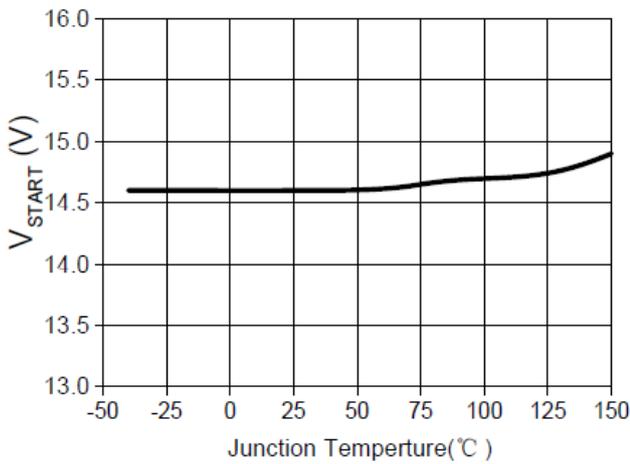
1. $R_{DS(on)}$ vs. T_J



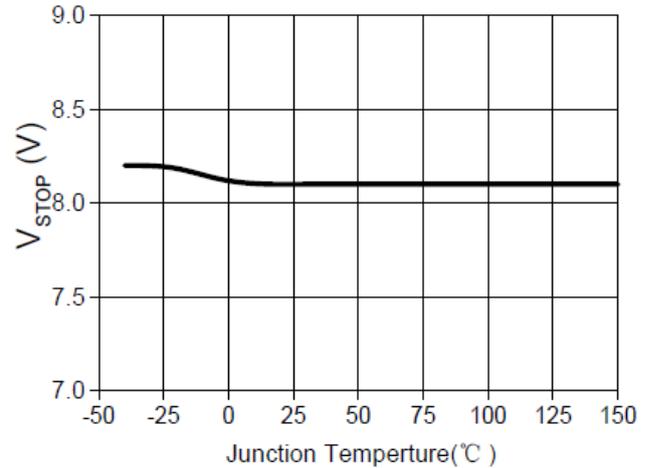
2. B_{VDSS} vs. T_J



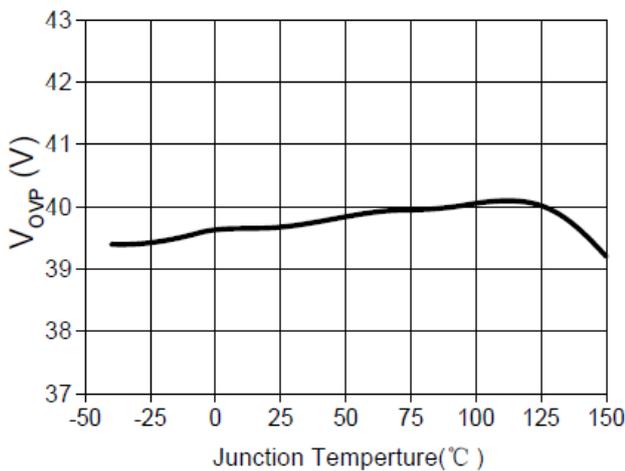
3. V_{START} vs. T_J



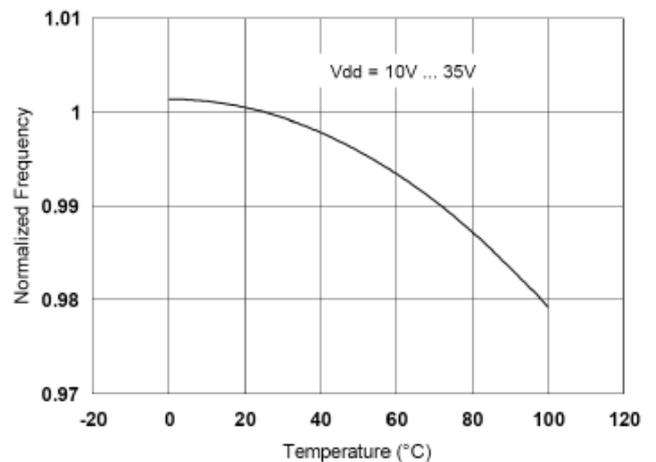
4. V_{STOP} vs. T_J



5. V_{OVP} vs. T_J



6. F_{osc} vs. Temperature





DETAILED INFORMATION

Functional Description

Startup

This device includes a high voltage start up current source connected on the SW of the device. As soon as a voltage is applied on the input of the converter, this start up current source is activated and to charge the V_{DD} capacitor as long as V_{DD} is lower than V_{START} . When reaching V_{START} , the start up current source is cut off and V_{DD} is sourced by auxiliary side. As V_{DD} falls below V_{STOP} , the HV-Start circuit won't work immediately until V_{DD} is lower than V_{RST} .

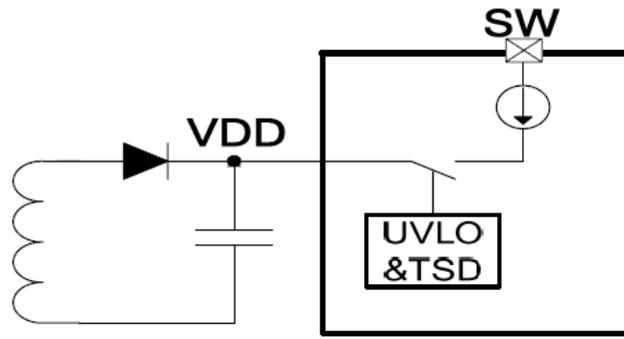


Fig 1. Startup circuit

Soft-start up

In the process of start up, the current of the drain increases to the maximum limitation step by step. As a result, it can reduce the stress of the secondary diode greatly and help to prevent the transformer from turning into the saturation state. Typically, the duration of soft-start is 7.5ms.

Gate driver

The internal power MOSFET in AP8022C is driven by a dedicated gate driver for power switch control. Too weak a gate driver strength results in higher conduction and switch loss of the MOSFET, while too strong a gate driver results in worse EMI.

A good tradeoff is achieved through the built-in totem pole gate design with proper output strength and dead time. The good EMI system design and low idle loss are easier to achieve with this dedicated control scheme.

Oscillator

The switching frequency of AP8022C is internally fixed at 60 kHz. No external frequency setting components are required for PCB design.

The frequency modulation is implemented in AP8022C. So, it minimizes the conduction band EMI and therefore eases the system design because the tone energy could be spread out.



Feed-back

A feedback pin controls the operation of the device. Unlike conventional PWM control circuits, which use a voltage input, the COMP pin is sensitive to current. Fig. 2 presents the internal current mode structure. The Power MOSFET delivers a sense current that is proportional to the main current. R2 receives this current, and the current comes from the COMP pin. The voltage across R2 (V_{R2}) is then compared to a fixed reference voltage. The MOSFET is switched off when V_{R2} equals the reference voltage.

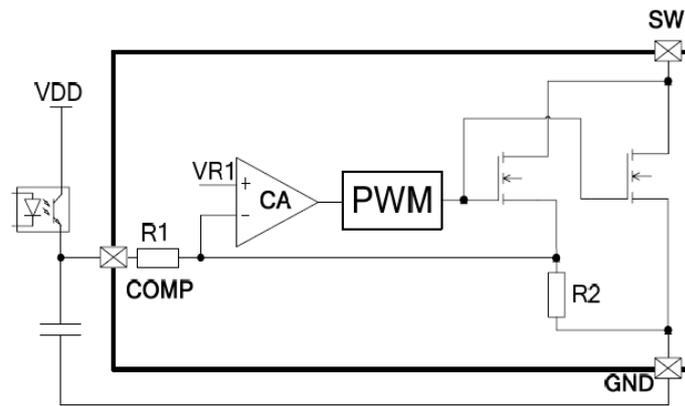


Fig 2. Feedback circuit

Leading Edge Blanking (LEB)

At the instant the internal Sense FET is turned on, there usually exists a high current spike through the Sense FET, caused by the primary side capacitance and secondary side rectifier diode reverse recovery. Excessive voltage across the sense resistor would lead to false feedback operation in the current-mode PWM control. To counter this effect, the device employs a leading-edge blanking (LEB) circuit. This circuit inhibits the PWM comparator for a short time (typically 300ns) after the Sense FET is turned on.

Under Voltage Lock Out

Once the fault condition occurs, switching is terminated, and the Sense FET remains off. This causes V_{DD} to fall. When V_{DD} reaches the V_{DD} reset voltage, 6V, the protection is reset, and the internal high voltage current source charges the V_{DD} capacitor. When V_{DD} reaches the UVLO start voltage, 14.5V, the device resumes its normal operation. In this manner, the auto-restart can alternately enable and disable the switching of the power Sense FET until the fault condition is eliminated.

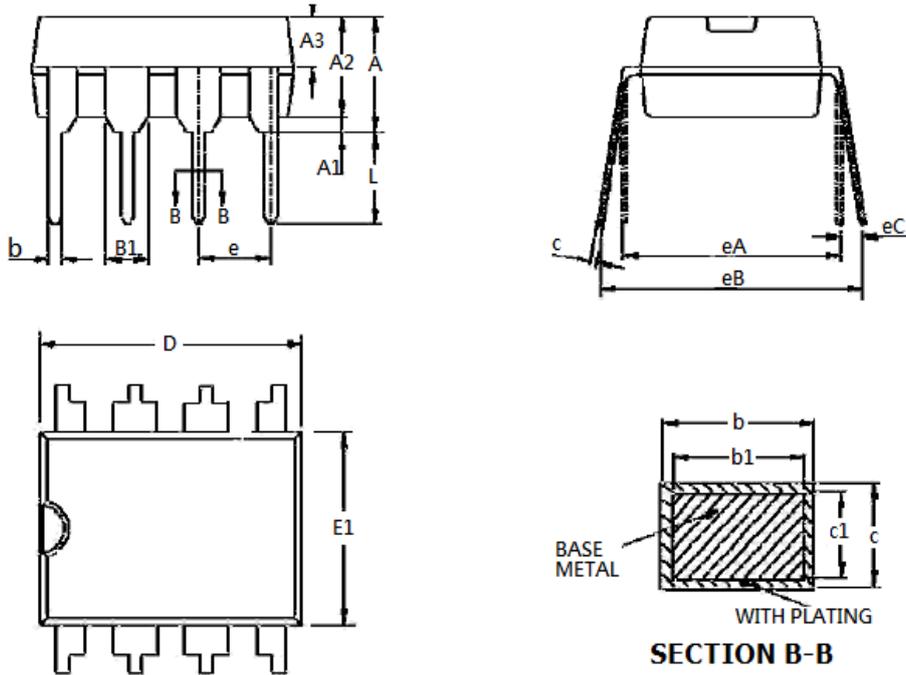
Thermal Shutdown (TSD, OTP)

The Sense FET and the control IC are integrated in the same chip, making it easier for the control IC to detect the temperature of the Sense FET. When the temperature exceeds approximately 170°C, thermal shutdown is activated, the device turns off the Sense FET. The device will go back to work when the lower threshold temperature of about 145°C is reached.



PACKAGE INFORMATION

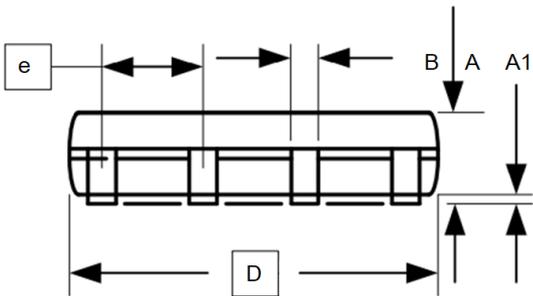
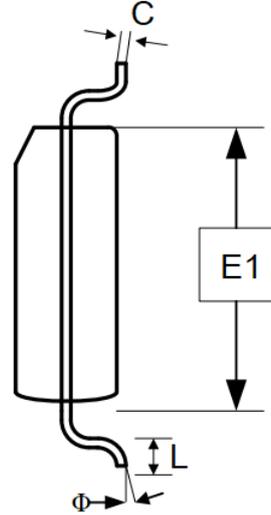
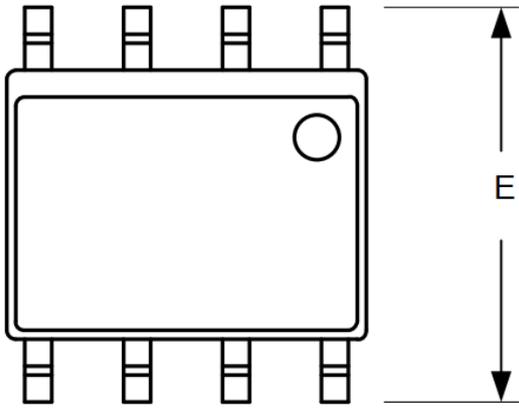
Dimension in DIP8 (Unit: mm)



Symbol	Min	Max
A	3.60	4.00
A1	0.51	-
A2	3.00	3.40
A3	1.55	1.65
b	0.44	0.53
b1	0.43	0.48
B1	1.52BSC	
c	0.24	0.32
c1	0.23	0.27
D	9.05	9.45
E1	6.15	6.55
e	2.54BSC	
eA	7.62BSC	
eB	7.62	9.30
eC	0.00	0.84
L	3.00	-



Dimension in SOP8 (Unit: mm)



Symbol	Min.	Max.
A	1.350	1.750
A1	0.100	0.230
B	0.390	0.480
C	0.210	0.260
D	4.700	5.100
E1	3.800	4.000
E	5.800	6.200
e	1.270 BSC	
L	0.500	0.800
Φ	0°	8°



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